

描述 / Descriptions

SOT-23 塑封封装 硅 PNP 数字三极管。Silicon PNP Digital transistor in a SOT-23 Plastic Package.

特征 / Features

内装偏置电阻，简化线路设计，减少元件和制造流程。无卤产品。

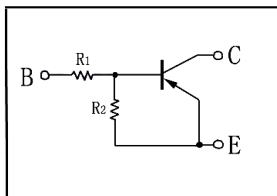
With built-in bias resistors, simplify circuit design, reduce a quantity of parts and manufacturing process. HF product.

用途 / Applications

用于开关、反相电路、界面电路以及驱动电路中。

Switching, inverter circuit, interface circuit and driver circuit applications.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN 1 : Base PIN 2 : Emitter PIN 3 : Collector

放大及印章代码 / h_{FE} Classifications & Marking

Marking	H13
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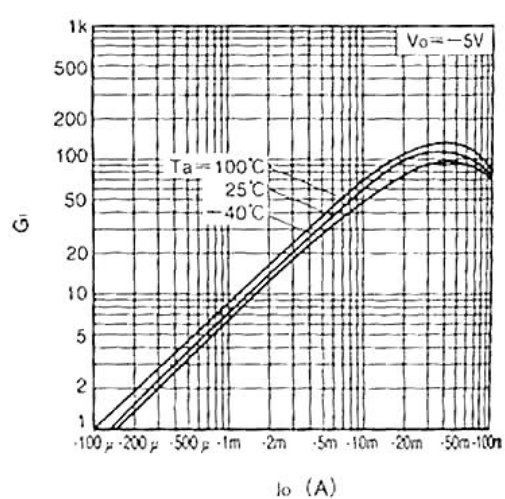
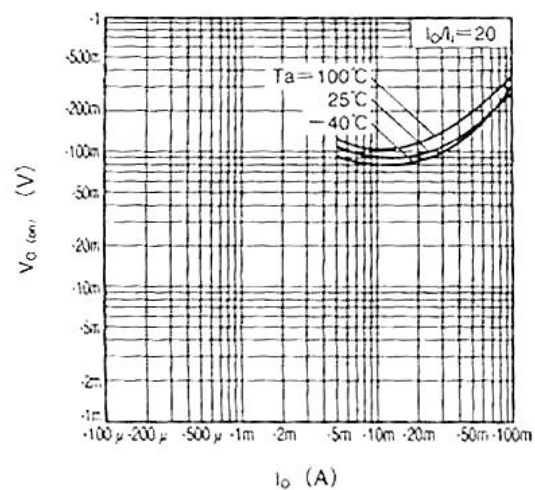
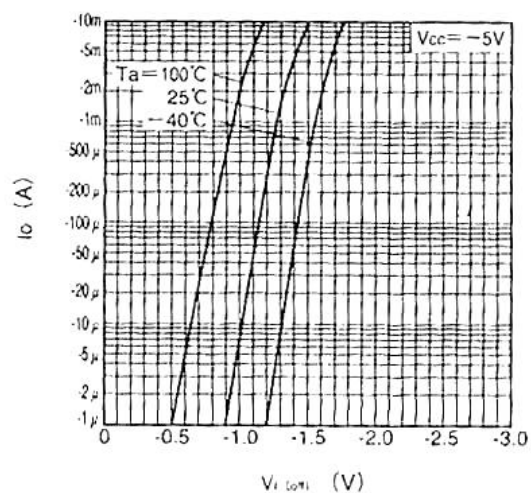
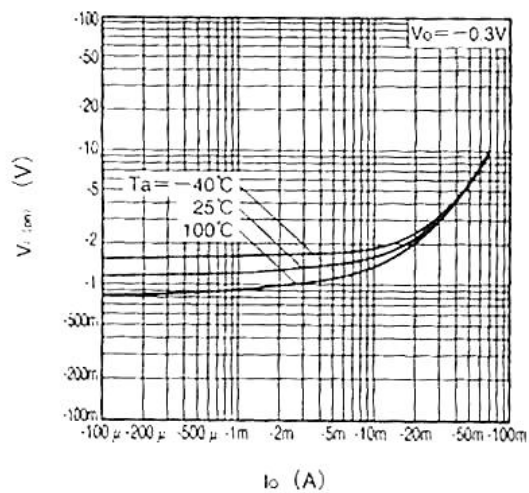
极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Output Voltage	V _{CC}	-50	V
Input Voltage	V _{IN}	-30	V
		10	V
Output Current	I _O	-100	mA
	I _{C(MAX)}	-100	mA
Power Dissipation	P _d	200	mW
Junction Temperature	T _j	150	°C
Storage Temperature Range	T _{stg}	-55~150	°C

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Input Voltage	V _{I(off)}	V _{CC} =-5.0V I _O =-100μA			-0.5	V
	V _{I(on)}	V _O =-0.3V I _O =-20mA	-3.0			V
Output Voltage	V _{O(on)}	I _O =-10mA I _I =-0.5mA		-0.1	-0.3	V
Input Current	I _I	V _I =-5.0V			-1.8	mA
Output Cut-off Current	I _{O(off)}	V _{CC} =-50V V _I =0V			-0.5	μA
DC Current Gain	G _I	V _O =-5.0V I _O =-10mA	20			
Transition Frequency	f _T	V _{CE} =-10V I _E =5.0mA f=100MHz		250		MHz
Resistance1	R ₁		3.29	4.7	6.11	KΩ
Resistance Ratio	R ₂ /R ₁		0.8	1.0	1.2	

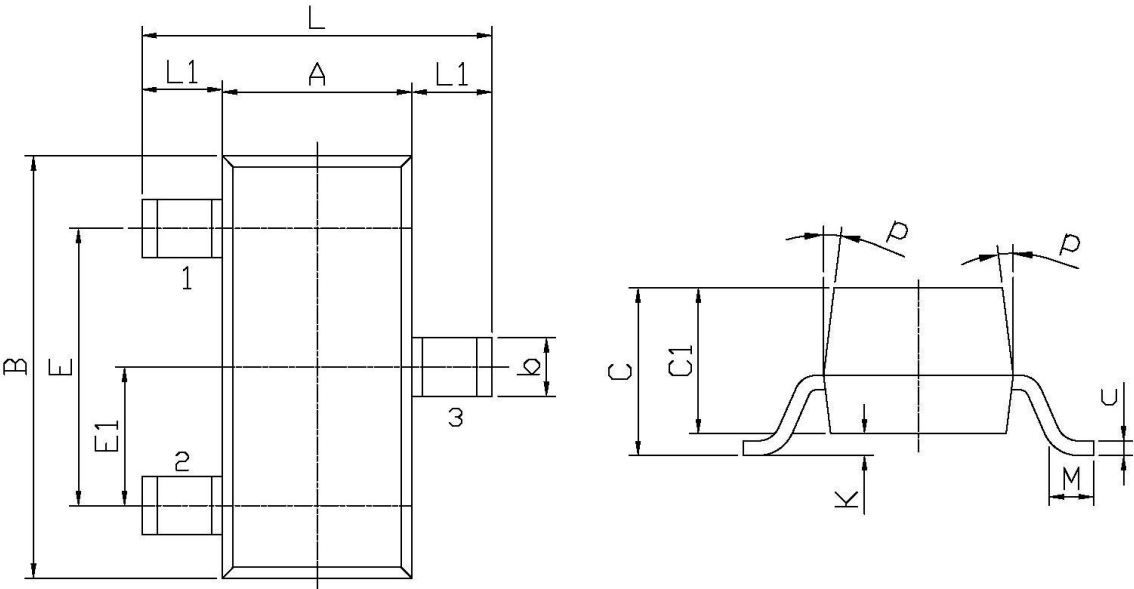
电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

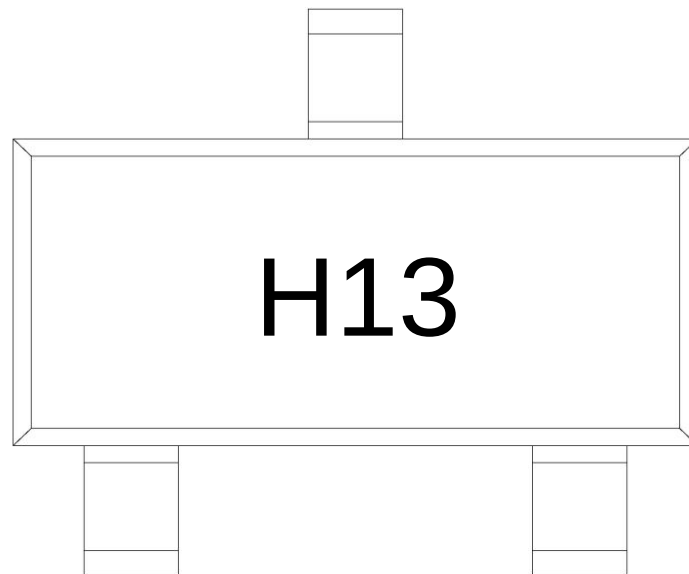
SOT-23

单位：mm



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
L	2.2	2.7	C	1.30Max	
L1	0.45	0.65	C1	0.90	1.20
A	1.15	1.50	c	0.05	0.20
B	2.70	3.10	K	0	0.10
E	1.70	2.10	M	0.20MIN	
E1	0.85	1.05	P	7°	
b	0.35	0.55			

印章说明 / Marking Instructions



说明：

H： 为公司代码

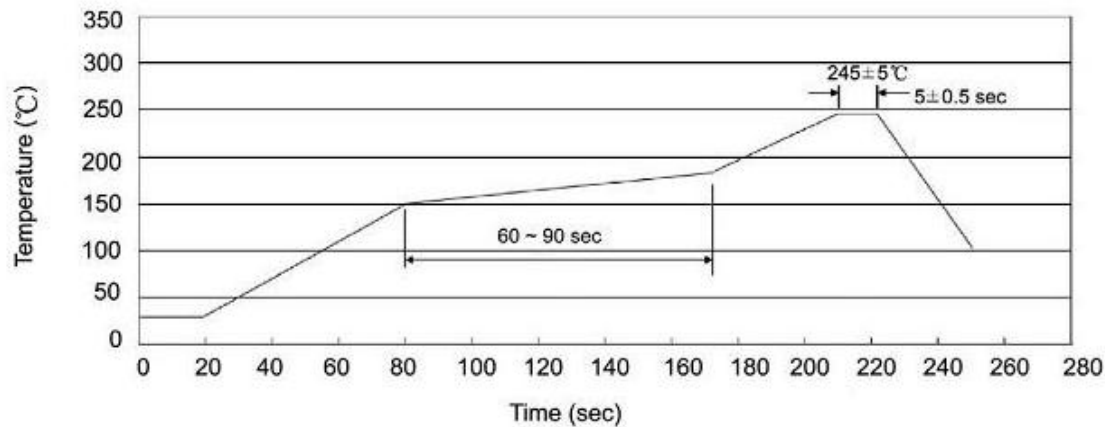
13： 为型号代码

Note:

H： Company Code

13： Product Type Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C 时间：10±1 sec. Temp.:260±5°C Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

使用说明 / Notices